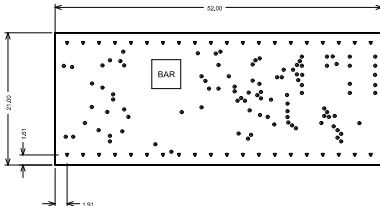


Symbol	Hit Count	Tool Size	Plated	Hole Type
○	102	0.3mm (11.81mil)	PTH	Round
▽	40	1mm (39.37mil)	PTH	Round
	142 Total			



1. MATERIALS/SPECIFICATIONS:
NOT SPECIFIED
2. LAYER BUILD:
K99
3. EXCEPTIONS:
a) STANDARD FINISH
b) TENTING VIA PADS: ACCEPTABLE TO ADD 50um
c) RESIST CLEARANCE AROUND PTH VIA HOLE EDGE.
4. OVERALL BOARD THICKNESS:
1.6mm
5. PROFILE ROUTING:
TO BE CUT USING 2.4mm DSA CUTTER.
TO DATA IN *.GPH
6. PANEL INFORMATION:
SEE SHEET 2 OF THIS DRAWING FOR DETAILS OF
MULTI-IMPRESSION PANEL REQUIREMENTS.
7. PHOTOFILES:
TOP SOLER MASK *.GTS
TOP COPPER *.GTL
BOTTOM COPPER *.GBL
BOTTOM SOLDER MASK *.GBS
NO MARK LAYER TOP *.GPD
PROFILE *.GPH
V-CUTS *.GVP

PLEASE STITCHED BOARD
ALL DIMENSIONS IN MILLIMETERS TO 420 MICRO-4200
DRAWING PROVIDED TO BE USED
FOR DATA DELIVERY ONLY. NOT FOR CONSTRUCTION.

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NO ANGLE PROJECTION
DO NOT SCALE



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FILE
LPC1114U24 NXP DEV BOARD

DRAWN BY
J1452

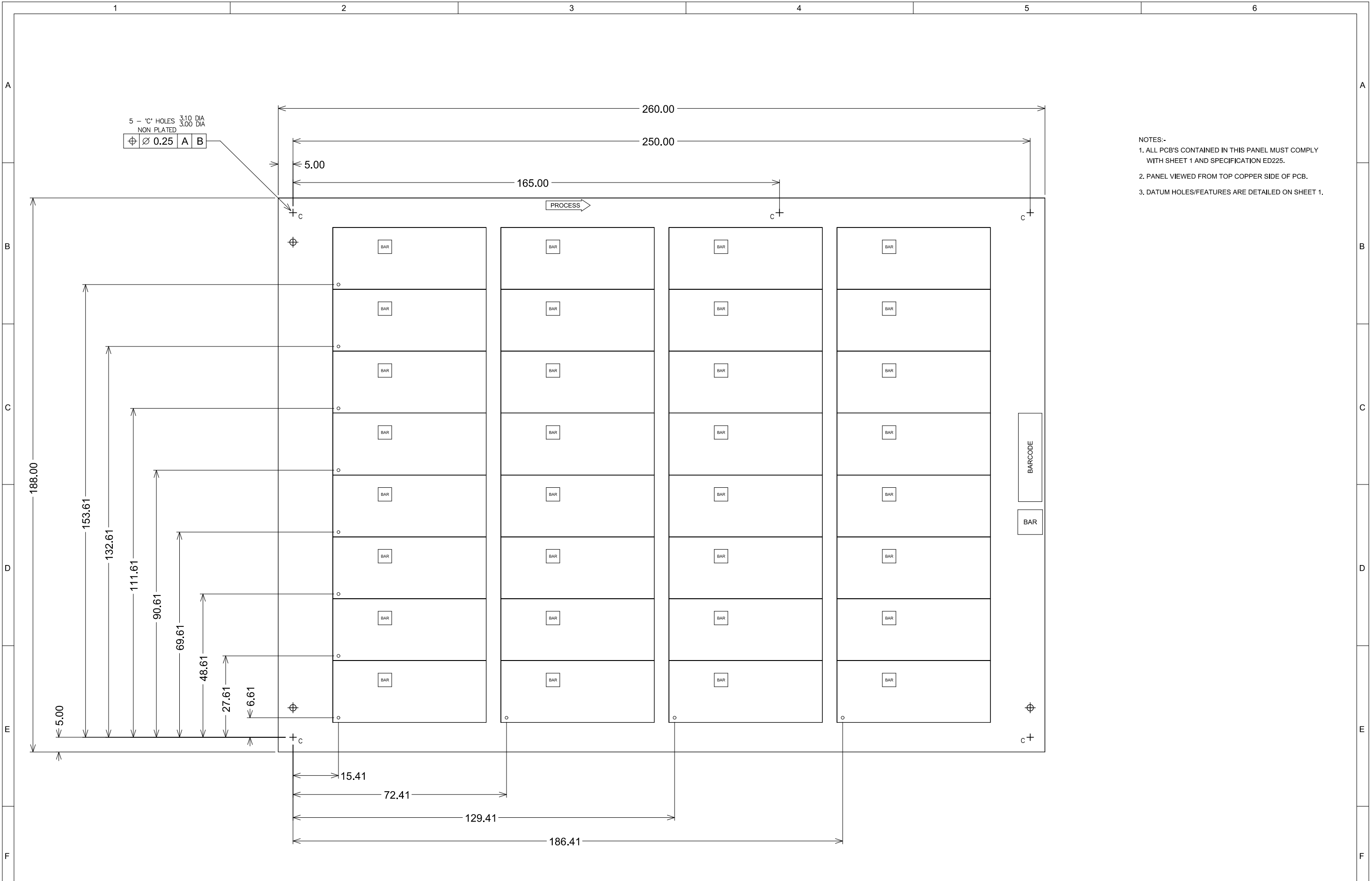
CHECKED
md131211

ORIGIN DATE
11/12/13

REVISION
D3

SHEET
1 of 2

DRAWING NO.
M-5694-0601-D3-A



- NOTES:-
1. ALL PCB'S CONTAINED IN THIS PANEL MUST COMPLY WITH SHEET 1 AND SPECIFICATION ED225.
 2. PANEL VIEWED FROM TOP COPPER SIDE OF PCB.
 3. DATUM HOLES/FEATURES ARE DETAILED ON SHEET 1.